

# P-Channel Enhancement Mode MOSFET

## 1. Product Information

### Features

- Advanced trench technology
- Excellent  $R_{DS(ON)}$
- Low gate charge

### Applications

- Battery protection
- Load switch
- Uninterruptible power supply

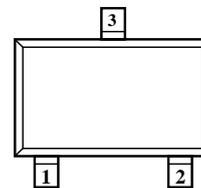
### Quick reference

- $V_{DS} \geq -60V$
- $I_D \leq -3.8A$
- $R_{DS(ON)} \leq 150m\Omega @ V_{GS} = -10V$  (Type: 125m $\Omega$ )

### Pin Description

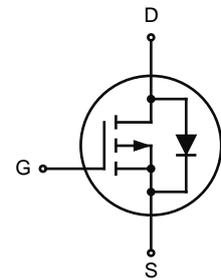
Pin	Description
1	Gate(G)
2	Source(S)
3	Drain(D)

### Simplified Outline



SOT-23-3L  
Top View

### Symbol



## Package Marking and Ordering Information

Product Name	Package	Marking	Reel Size	Tape width	Quantity
KJ3P06S	SOT-23-3L	<b>W3P6</b> YWWXXX: Date Code			3000

## 2. Absolute Maximum Ratings ( $T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-3.8	A
$I_D@T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-2.4	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-12	A
$P_D@T_A=25^\circ C$	Total Power Dissipation <sup>3</sup>	1.5	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	125	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	80	$^\circ C/W$

**3. Electrical Characteristics** (T<sub>J</sub>=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-60	-67	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =-1mA	---	-0.021	---	V/°C
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-1.5A	---	125	150	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-1A	---	158	200	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-1.0	1.7	-2.5	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	4.08	---	mV/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-48V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =-48V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C	---	---	5	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =-5V, I <sub>D</sub> =-1.5A	---	5.9	---	S
Q <sub>g</sub>	Total Gate Charge (-4.5V)	V <sub>DS</sub> =-20V, V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-1.5A	---	4.6	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	1.4	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	1.62	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DS</sub> =-15V, V <sub>GS</sub> =-10V, R <sub>G</sub> =3.3Ω, I <sub>D</sub> =-1A	---	17.4	---	ns
T <sub>r</sub>	Rise Time		---	5.4	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	37.2	---	
T <sub>f</sub>	Fall Time		---	2.4	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, f=1MHz	---	531	---	pF
C <sub>oss</sub>	Output Capacitance		---	59	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	38	---	
I <sub>S</sub>	Continuous Source Current <sup>1,4</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	-1.7	A
I <sub>SM</sub>	Pulsed Source Current <sup>2,4</sup>		---	---	-7	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =-1A, T <sub>J</sub> =25°C	---	---	-1.2	V

**Note :**

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed, pulse width ≦ 300us, duty cycle ≦ 2%
- 3、The power dissipation is limited by 150°C junction temperature
- 4、The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation.

## 4. Typical Characteristics

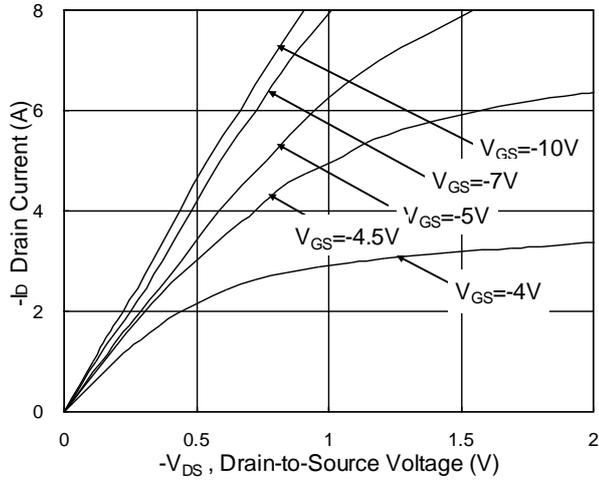


Fig.1 Typical Output Characteristics

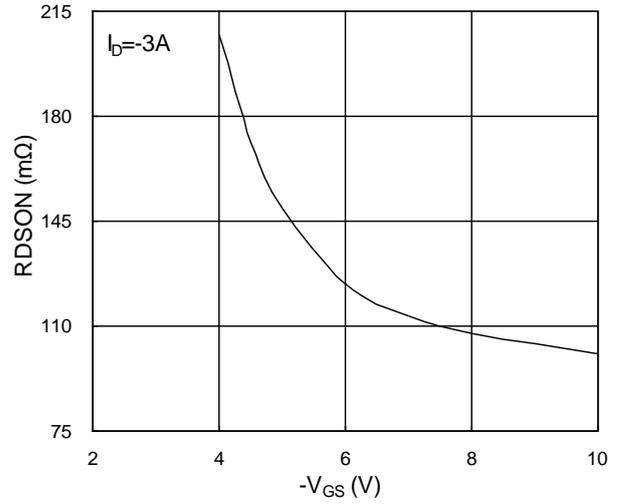


Fig.2 On-Resistance vs. G-S Voltage

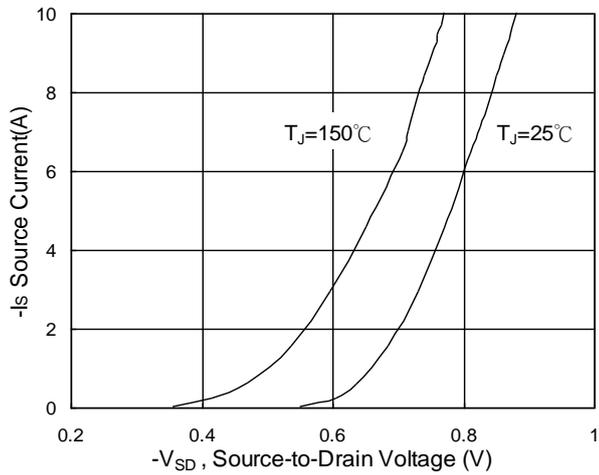


Fig.3 Forward Characteristics Of Reverse

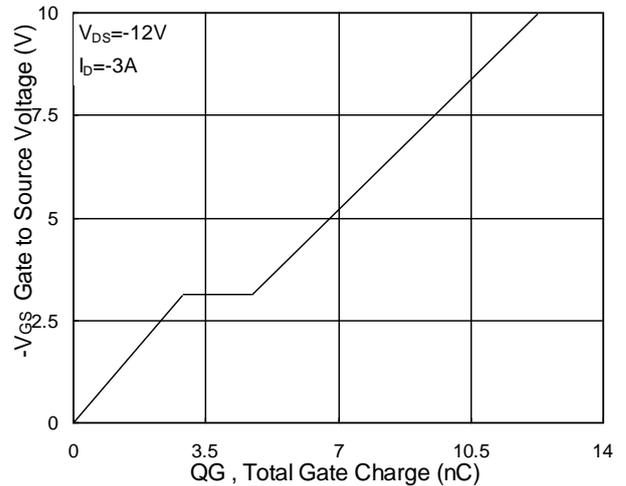


Fig.4 Gate-Charge Characteristics

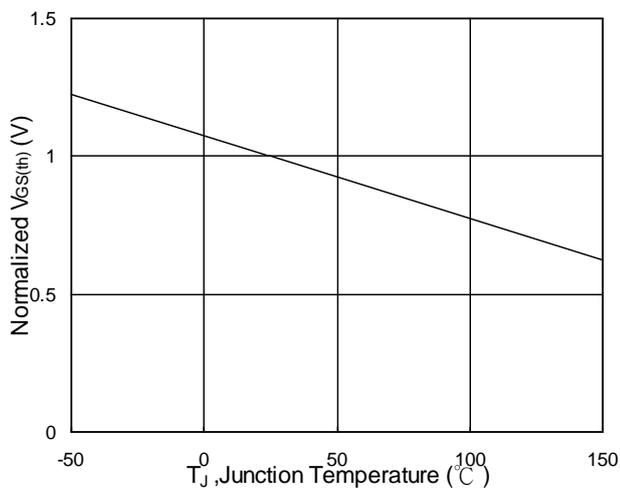


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

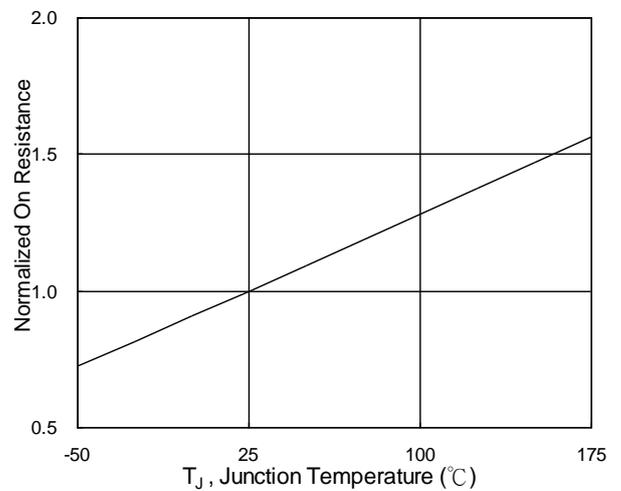


Fig.6 Normalized  $R_{DSON}$  vs.  $T_J$

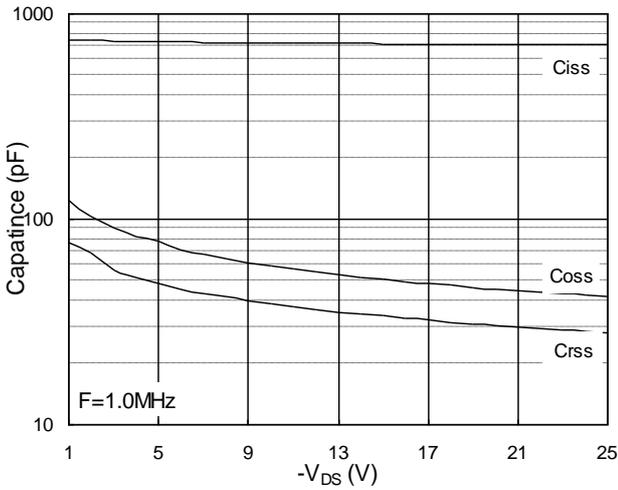


Fig.7 Capacitance

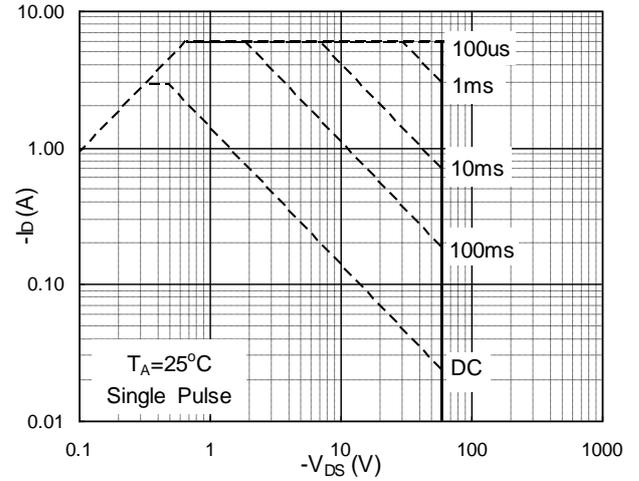


Fig.8 Safe Operating Area

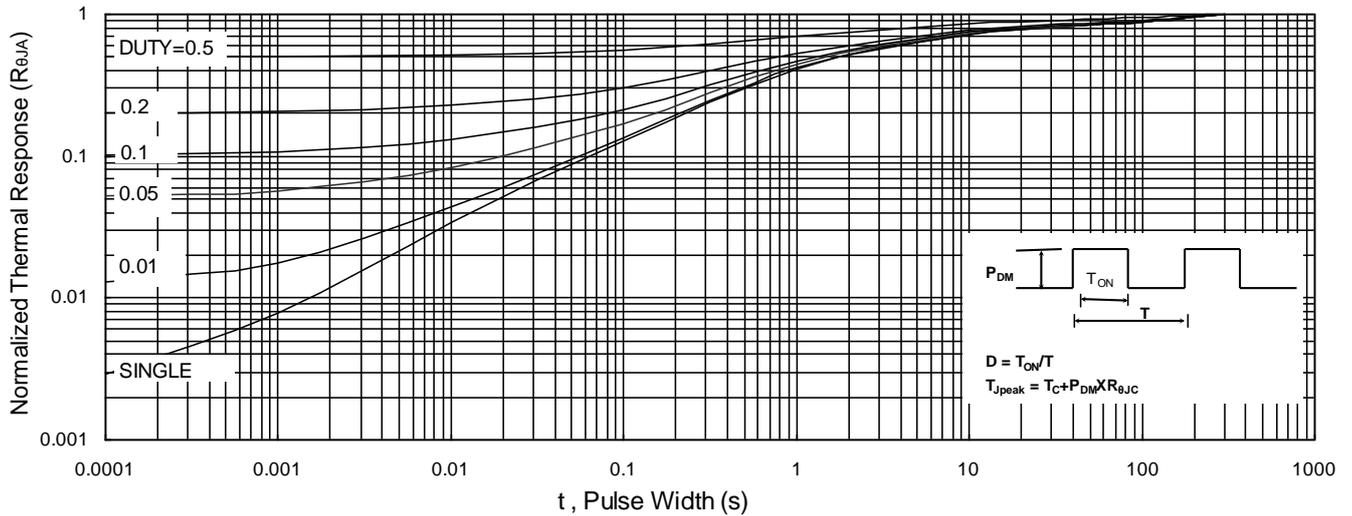


Fig.9 Normalized Maximum Transient Thermal Impedance

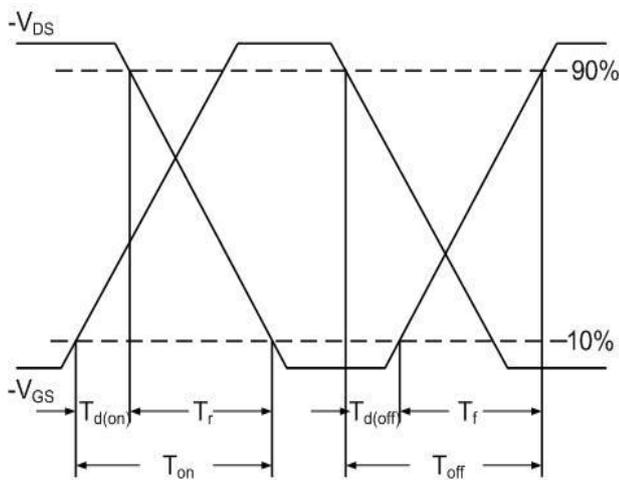


Fig.10 Switching Time Waveform

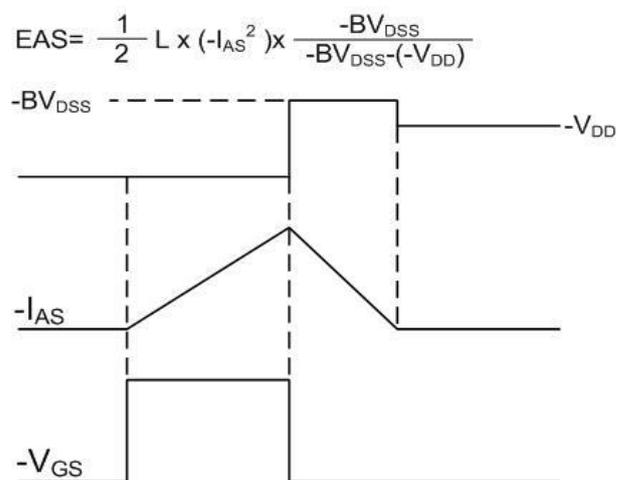
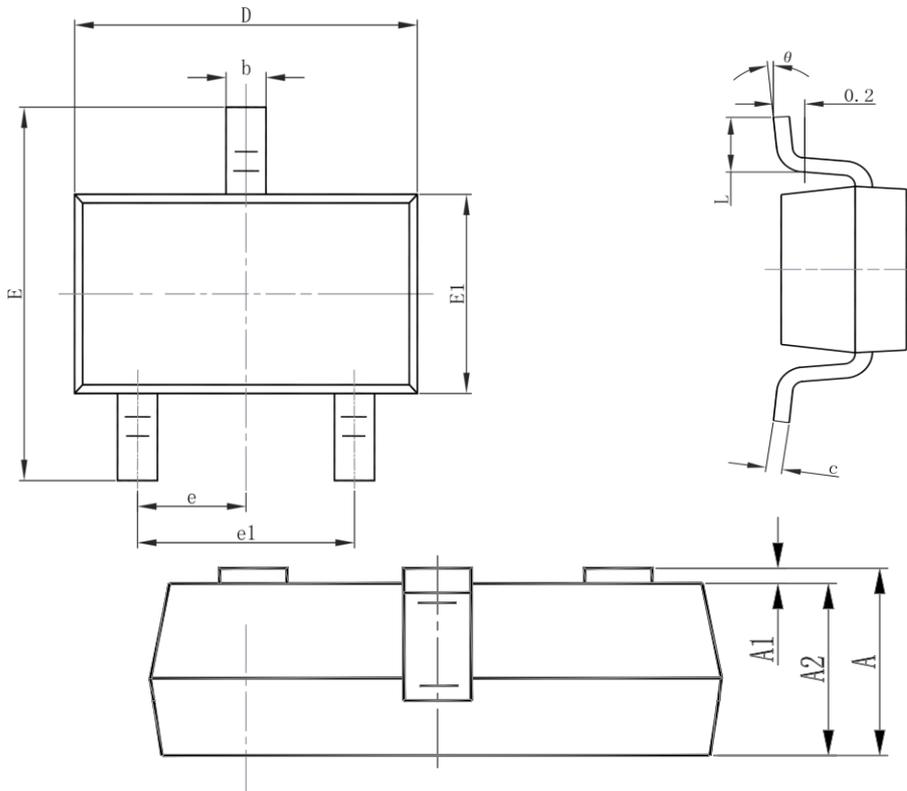


Fig.11 Unclamped Inductive Waveform

**5.Package Mechanical Data**

SOT-23-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°